

AMENDMENTS TO THE CLAIMS

Claim 1. (Currently Amended)

A semiconductor device comprising:

a semiconductor substrate ~~on which~~ having a front surface and rear surface, a photoelectric converting portion is being formed on the front surface;

a light-shading means for shading an incoming light ~~reflected from a~~ the rear surface of the semiconductor substrate to said photoelectric converting portion, wherein

said light-shading means is formed at an area corresponding to at least the photoelectric converting portion, said area ~~being on the side of~~ the rear surface of the semiconductor substrate.

Claim 2. (Original)

A semiconductor device according to claim 1, wherein said package comprises a wiring board with a connecting terminal formed on the rear surface.

Claim 3. (Original)

A semiconductor device according to claim 1 or 2, wherein said light shading means is rough surface area.

Claim 4. (Original)

A semiconductor device according to claim 1 or 2, wherein said light shading means is a multi-layer film composed of films with different refraction indices formed on the area corresponding to the photoelectric converting portion on the rear surface of said semiconductor substrate.

Claim 5. (Original)

A semiconductor device according to claim 1 or 2, wherein said light shading means is a light-shading film formed on the rear surface of said semiconductor substrate.

Claim 6. (Original)

A semiconductor device according to claim 1 or 2, wherein said wiring board is connected to said semiconductor substrate through a light-shading resin material.

Claim 7. (Original)

A semiconductor device according to claim 1 or 2, wherein a surface of said wiring board is rough surface.

Claim 8. (Previously Presented)

A semiconductor device according to claims 1 or 2, wherein said wiring board includes a light shading layer in the interior or on the rear surface of the semiconductor substrate.

Claim 9. (Previously Presented)

A method for manufacturing a semiconductor device comprising the steps of:

a forming step for forming a plurality of semiconductor devices on the front surface of a semiconductor substrate;

a bonding step for bonding a wiring board on the rear surface of said semiconductor substrate;

a separating step for separating a bonding structure, obtained by bonding, into semiconductor devices; and

a grinding step for forming rough surface on the rear surface of the semiconductor substrate.

Claim 10. (Previously Presented)

A method for manufacturing a semiconductor device comprising the steps of:

a forming step for forming a plurality of semiconductor devices on the front surface of a semiconductor substrate;

a bonding step for bonding a wiring board on the rear surface of said semiconductor substrate using light-shading adhesive the light-shading adhesive suppressing light reflected from the rear surface of the semiconductor substrate from reaching the semiconductor device; and

a separating step for separating a bonding structure obtained by bonding, into said semiconductor devices.